

Title (en)

Manufacturing method for a permanent magnet, moulding system and permanent magnet

Title (de)

Herstellungsverfahren für ein Permanentmagnet, Formsystern und Permanentmagnet

Title (fr)

Procédé de fabrication d'aimant permanent, système de moulage et aimant permanent

Publication

**EP 2605253 A1 20130619 (EN)**

Application

**EP 11193247 A 20111213**

Priority

EP 11193247 A 20111213

Abstract (en)

It is described a method for manufacturing a permanent magnet, the method comprising: separating, by a separator (107, 207), a mould volume into a first compartment (109, 209) and a second compartment (111, 211); filling a first material (119, 219) into the first compartment (109, 209); filling a second material (121, 221) into the second compartment (111, 211); compacting the first material and the second material, wherein the separator is shaped such that a shape of the first compartment corresponds to a target shape of the magnet.

IPC 8 full level

**H01F 7/02** (2006.01); **H01F 1/057** (2006.01); **H01F 41/02** (2006.01)

CPC (source: EP)

**H01F 7/0221** (2013.01); **H01F 41/026** (2013.01); **H01F 41/0266** (2013.01); **H01F 1/0577** (2013.01)

Citation (applicant)

- EP 2017859 A1 20090121 - SIEMENS AG [DE]
- WO 2010066251 A1 20100617 - SINTEX AS [DK], et al

Citation (search report)

- [XY] EP 1300208 A2 20030409 - DELPHI TECH INC [US]
- [XY] EP 1300210 A2 20030409 - DELPHI TECH INC [US]
- [Y] EP 1712652 A1 20061018 - SHINETSU CHEMICAL CO [JP]
- [A] US 2006170301 A1 20060803 - MASUZAWA MASAHIRO [JP], et al
- [A] US 5722032 A 19980224 - GAY DAVID EARL [US]
- [A] EP 2378634 A1 20111019 - SIEMENS AG [DE]

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

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DOCDB simple family (application)

**EP 11193247 A 20111213**; CN 201210537415 A 20121213; DK 11193247 T 20111213; EP 2012075049 W 20121211